

Title (en)

POLISHING DEVICE AND POLISHING METHOD

Title (de)

POLIERVORRICHTUNG UND POLIERVERFAHREN

Title (fr)

DISPOSITIF DE POLISSAGE ET PROCÉDÉ DE POLISSAGE

Publication

**EP 3053703 A4 20170726 (EN)**

Application

**EP 14851309 A 20141002**

Priority

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- JP 2014076360 W 20141002

Abstract (en)

[origin: EP3053703A1] It is an objective of the present invention to provide a polishing device and a polishing method that allows for polishing of workpieces having various contours. The polishing device includes a motor movement mechanism (33) and a second motor (30) that rotates a workpiece (K). The motor movement mechanism (33) moves the workpiece (K) in a direction tangential to a radially outer circumferential surface of a polishing member (10) and moves the workpiece (K) in a direction orthogonal to a rotational axis of the polishing member (10).

IPC 8 full level

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CPC (source: EP KR US)

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Citation (search report)

- [X] US 4667443 A 19870526 - SAKURAI KAORU [JP], et al
- [A] EP 2537634 A1 20121226 - WENDT GMBH [DE]
- See references of WO 2015050186A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

**EP 3053703 A1 20160810**; **EP 3053703 A4 20170726**; CN 105658377 A 20160608; JP 2018001406 A 20180111; JP WO2015050186 A1 20170309; KR 20160067106 A 20160613; TW 201529224 A 20150801; US 2016236314 A1 20160818; WO 2015050186 A1 20150409

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